

L Number	Hits	Search Text	DB	Time stamp
1	18	p adj n adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:16
2	572	vertical adj junction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:21
3	2	("3018313" "4042417").PN.	USPAT	2004/07/23 08:17
4	2	("3018313" "4042417").PN.	USPAT	2004/07/23 08:21
5	10	4332973.URPN.	USPAT	2004/07/23 08:21
6	10	(vertical adj junction) and extrud\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:22
7	9	(vertical adj junction) and extrusion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:28
8	1	("3690953").PN.	USOCR	2004/07/23 08:28
9	7	wafer same extru\$5 same p same n	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:30
10	119	wafer near2 extru\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:37
11	199	semiconductor near2 extru\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:03
12	0	jp-10-178218-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:03
13	2	jp-10178218-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:08
14	8	pn adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:09
15	7	np adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:10

16	29	semiconductor same extru\$5 same grain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:45
17	1511	p same n same extru\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:34
18	20	p same n same extru\$5 same junction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:17
19	19	p same n same extru\$5 same grain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:18
20	10	p same n same extru\$5 same boundary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:19
21	631	p same n same die same semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:24
22	14	p same n same die same semiconductor same press\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:25
23	293	((solar adj (cell or battery or module)) or photovoltaic) same fabric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:27
24	5	p same n same extru\$ same bundl\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:34
25	5	pn adj fiber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:46
26	233	semiconductor adj fiber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 09:55
27	61	vertical adj junction	USOCR	2004/07/23 10:00
28	2	jp-11204843-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:01

29	2	us-5959341-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:02
30	2	jp-62264682-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:02
31	2	jp-10112558-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:03
32	2	jp-10178558-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:03
33	0	jp-1017218-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:03
34	2	jp-10178218-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:04
35	2	us-6147293-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:05
36	2	(extruded adj wafer) same semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:06
37	58	thermoelectric same wafer same n same p	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:35
38	17	thermoelectric same wafer same die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:27
39	457	thermoelectric same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:27
40	64	thermoelectric near2 wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:27

41	164	n near2 p near2 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:37
42	62	n near2 p near2 fiber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:39
43	17	(p near1 fiber) same (n near1 fiber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 10:39
-	4	extrud\$3 same wafer same p same n	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 07:55
-	25	extrud\$3 same p same n same semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:04
-	1	jp-11340530-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 08:14